

RF DIN 1.0/2.3 Modular Backplane System

molex

First-to-market RF DIN 1.0/2.3 Modular Backplane System delivers 75 Ohm impedance and expansion capability up to 10 ports for superior orthogonal PCB mating flexibility in video and broadcast applications

PCB developers for video, commercial broadcast, and telecommunications now have the ability to transfer multiple RF signals across mated boards with a 1.00mm axial positioning tolerance.

The RF DIN 1.0/2.3 Modular Backplane System enables system designers to improve system routing of RF signals for board-to-board communications. The first-to-market modular backplane design employs a bracket housing concept that can be expanded to accommodate a wide range of RF ports, from two to ten.

Customers currently using DIN connectors can begin backplane implementations, achieving space consolidation in converging video, data, and voice applications.



RF DIN 1.0/2.3 Modular Backplane System (Headers and Daughtercard Receptacles Shown Mated)

Features and Advantages

Modular, bracketed housing design — four ports currently available; six, eight and ten ports available upon demand

Enables customer-configurable options. Rapid response for customer solutions

Subminiature design based on DIN 1.0/2.3 connectors

Ideal where space limitation is a factor

75 Ohm contacts available; 50 Ohm contacts available upon demand

Supports a wide range of applications

DIN 1.0/2.3 interface allows up to 1.00mm of axial engagement tolerance

Provides excellent flexibility when mating orthogonal PCBs. Enables transferring multiple RF signals across mated boards in a single assembly

Plastic housing engages before RF contact

Prevents damage from stubbing

Slide-on coupling design

Allows quick installation

Frequency DC to 3 GHz

Ideal for CATV, communication systems and high-density radio applications

Applications

Datacommunication and

Telecommunication Applications

Base Stations

Servers

Video / CATV

Head End Equipment

Video Servers



Server Chassis

RF DIN 1.0/2.3 Modular Backplane System

Specifications

REFERENCE INFORMATION

Packaging: Tray
Designed In: mm
RoHS: Yes
Halogen Free: Yes
Conform to: CECC 22 230, DIN 47297 and DIN 41626

ELECTRICAL

Frequency Range: DC to 2 GHz
Voltage, Working: 250V rms
Nominal Impedance:
75 Ohms currently available
50 Ohms available upon demand
Center Contact Resistance: 6 mΩ
VSWR at Max. Frequency: 1.22

MECHANICAL

Coupling Method: Slide-on
Force to Engage (max.): 9.96 N
Force to Disengage (min.): 0.89 N
Durability (min.): 500 cycles

PHYSICAL

Operating Temperature:
-40 to +85 °C
Axial float: 1.00 mm

Additional Product Features



Easy Slide-on Coupling of Connectors

Ordering Information

Order No.	Component	ConnectorType	Port Size	Gender	Impedance (Ohms)	Orientation
73358-0980	Header	1.0/2.3	1-by-4	Male	75	Right Angle
73174-1020	Daughtercard Receptacle		-	Female		Vertical

www.molex.com/link/rfdinbackplane.html

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